

ABSTRACT

A semiconductor mounting arrangement inclusive of a heat sink member enabling desirable resistance to physical impact damage to the semiconductor device, the heat sink and the printed circuit board supporting the semiconductor device and the heat sink. The heat sink is fabricated of thermally and electrically conductive metal such as copper and captured by metallic interconnection such as soldering to conductors of the printed circuit board. Efficient thermal and electrical conductivity between semiconductor device and heat sink are achieved also by metallic interconnection such as soldering intermediate the semiconductor device and the heat sink. Desirable semiconductor device performance under extreme electrical and physical force transient loading conditions are disclosed.